winbond

8-BIT MICROCONTROLLER

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1. GENERAL DESCRIPTION

The W78L051C is an 8-bit microcontroller which can accommodate a wide supply voltage range with low power consumption. The instruction set for the W78L051C is fully compatible with the standard 8051. The W78L051C contains an 4K bytes Flash EPROM; a 128 bytes RAM; four 8-bit bi-directional and bit-addressable I/O ports; an additional 4-bit I/O port P4; two 16-bit timer/counters; a hardware watchdog timer and a serial port. These peripherals are supported by seven sources two-level interrupt capability. To facilitate programming and verification, the Flash EPROM inside the W78L051C allows the program memory to be programmed and read electronically. Once the code is confirmed, the user can protect the code for security.

The W78L051C microcontroller has two power reduction modes, idle mode and power-down mode, both of which are software selectable. The idle mode turns off the processor clock but allows for continued peripheral operation. The power-down mode stops the crystal oscillator for minimum power consumption. The external clock can be stopped at any time and in any state without affecting the processor.

2. FEATURES

- Fully static design 8-bit CMOS microcontroller
- Wide supply voltage of 2.4V to 5.5V
- 128 bytes of on-chip scratchpad RAM
- 4 KB electrically erasable/programmable Flash EPROM
- 64 KB program memory address space
- 64 KB data memory address space
- Four 8-bit bi-directional ports
- One extra 4-bit bit-addressable I/O port, additional $\overline{INT2}$ / $\overline{INT3}$ (available on 44-pin PLCC/QFP package)
- Two 16-bit timer/counters
- One full duplex serial port (UART)
- Watchdog Timer
- seven sources, two-level interrupt capability
- EMI reduction mode
- Built-in power management
- Code protection mechanism
- Packages:
  - Lead Free (RoHS) DIP 40: W78L051C24DL
  - Lead Free (RoHS) PLCC 44: W78L051C24PL
  - Lead Free (RoHS) PQFP 44: W78L051C24FL

4. PIN DESCRIPTION

SYMBOL	DESCRIPTIONS
$\overline{EA}$	**EXTERNAL ACCESS ENABLE**: This pin forces the processor to execute out of external ROM. It should be kept high to access internal ROM. The ROM address and data will not be presented on the bus if $\overline{EA}$ pin is high and the program counter is within on-chip ROM area.
$\overline{PSEN}$	**PROGRAM STORE ENABLE**: $\overline{PSEN}$ enables the external ROM data onto the Port 0 address/ data bus during fetch and MOVC operations. When internal ROM access is performed, no $\overline{PSEN}$ strobe signal outputs from this pin.
ALE	**ADDRESS LATCH ENABLE**: ALE is used to enable the address latch that separates the address from the data on Port 0.
RST	**RESET**: A high on this pin for two machine cycles while the oscillator is running resets the device.
XTAL1	**CRYSTAL1**: This is the crystal oscillator input. This pin may be driven by an external clock.
XTAL2	**CRYSTAL2**: This is the crystal oscillator output. It is the inversion of XTAL1.
V_{SS}	**GROUND**: Ground potential
V_{DD}	**POWER SUPPLY**: Supply voltage for operation.
P0.0–P0.7	**PORT 0**: Port 0 is a bi-directional I/O port which also provides a multiplexed low order address/data bus during accesses to external memory. The Port 0 is also an open-drain port and external pull-ups need to be connected while in programming.
P1.0–P1.7	**PORT 1**: Port 1 is a bi-directional I/O port with internal pull-ups. The bits have alternate functions which are described below: T2(P1.0): Timer/Counter 2 external count input T2EX(P1.1): Timer/Counter 2 Reload/Capture control
P2.0–P2.7	**PORT 2**: Port 2 is a bi-directional I/O port with internal pull-ups. This port also provides the upper address bits for accesses to external memory.
P3.0–P3.7	**PORT 3**: Port 3 is a bi-directional I/O port with internal pull-ups. All bits have alternate functions, which are described below: RXD(P3.0) : Serial Port receiver input TXD(P3.1) : Serial Port transmitter output $\overline{INT0}$ (P3.2) : External Interrupt 0 $\overline{INT1}$(P3.3) : External Interrupt 1 T0(P3.4) : Timer 0 External Input T1(P3.5) : Timer 1 External Input $\overline{WR}$ (P3.6) :External Data Memory Write Strobe $\overline{RD}$ (P3.7) : External Data Memory Read Strobe
P4.0–P4.3	**PORT 4:** Another bit-addressable bidirectional I/O port P4. P4.3 and P4.2 are alternative function pins. It can be used as general I/O port or external interrupt input sources ($\overline{INT2}$ / $\overline{INT3}$).

2. PORT4

Another bit-addressable port P4 is also available and only 4 bits (P4<3:0>) can be used. This port address is located at 0D8H with the same function as that of port P1, except the P4.3 and P4.2 are alternative function pins. It can be used as general I/O pins or external interrupt input sources ($\overline{INT2}$, $\overline{INT3}$).

Example:

```
P4      REG   0D8H
MOV     P4, #0AH      ; Output data "A" through P4.0–P4.3.
MOV     A, P4         ; Read P4 status to Accumulator.
ORL     P4.#00000001B ; Set P4.0 to be high state
ANL     P4.#11111110B ; Clear P4.0 to be low state.
```

3. Reduce EMI Emission

Because of on-chip Flash EPROM, when a program is running in internal ROM space, the ALE will be unused. The transition of ALE will cause noise, so it can be turned off to reduce the EMI emission if it is useless. Turning off the ALE signal transition only requires setting the bit 0 of the AUXR SFR, which is located at 08Eh. When ALE is turned off, it will be reactivated when the program accesses external ROM/RAM data or jumps to execute an external ROM code. The ALE signal will turn off again after it has been completely accessed or the program returns to internal ROM code space. The AO bit in the AUXR register, when set, disables the ALE output. In order to reduce EMI emission from oscillation circuitry, W78L051C allows user to diminish the gain of on-chip oscillator amplifiers by using programmer to clear the B7 bit of security register. Once B7 is set to 0, a half of gain will be decreased. Care must be taken if user attempts to diminish the gain of oscillator amplifier, reducing a half of gain may effect to external crystal operating improperly at high frequency above 20 MHz. The value of R and C1, C2 may need some adjustment while running at lower gain.

*****AUXR - Auxiliary register (8EH)**

-	-	-	-	-	-	-	AO

AO: Turn off ALE output.

4. Power-off Flag

*****PCON - Power control (87H)**

-	**-**	-	**POF**	GF1	GF0	PD	IDL

POF: Power off flag. Bit is set by hardware when power on reset. It can be cleared by software to determine chip reset is a warm boot or cold boot.

GF1, GF0: These two bits are general-purpose flag bits for the user.

PD: Power down mode bit. Set it to enter power down mode.

IDL: Idle mode bit. Set it to enter idle mode.

The power-off flag is located at PCON.4. This bit is set when V_{DD} has been applied to the part. It can be used to determine if a reset is a warm boot or a cold boot if it is subsequently reset by software.

Watchdog Timer

The Watchdog timer is a free-running timer which can be programmed by the user to serve as a system monitor, a time-base generator or an event timer. It is basically a set of dividers that divide the system clock. The divider output is selectable and determines the time-out interval. When the time-out occurs a system reset can also be caused if it is enabled. The main use of the Watchdog timer is as a system monitor. This is important in real-time control applications. In case of power glitches or electro-magnetic interference, the processor may begin to execute errant code. If this is left unchecked the entire system may crash. The watchdog time-out selection will result in different time-out values depending on the clock speed. The Watchdog timer will de disabled on reset. In general, software should restart the Watchdog timer to put it into a known state. The control bits that support the Watchdog timer are discussed below.

Watchdog Timer Control Register

Bit:	7	6	5	4	3	2	1	0
	ENW	CLRW	WIDL	-	-	PS2	PS1	PS0

Mnemonic: WDTC Address: 8FH

ENW : Enable watch-dog if set.

CLRW: Clear watch-dog timer and prescaler if set. This flag will be cleared automatically

WIDL : If this bit is set, watch-dog is enabled under IDLE mode. If cleared, watch-dog is disabled under IDLE mode. Default is cleared.

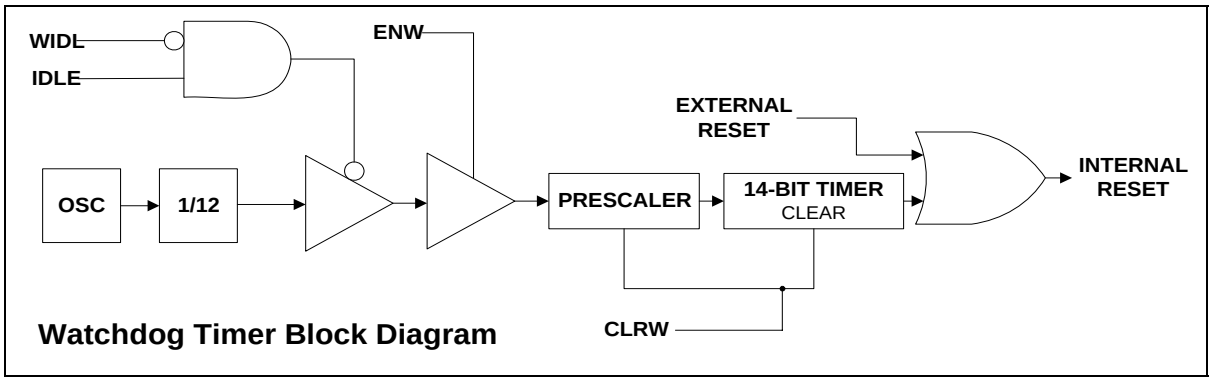
PS2, PS1, PS0: Watch-dog prescaler timer select. Prescaler is selected when set PS2–0 as follows:

PS2	PS1	PS0	PRESCALER SELECT
0	0	0	2
0	0	1	4
0	1	0	8
0	1	1	16
1	0	0	32
1	0	1	64
1	1	0	128
1	1	1	256

The time-out period is obtained using the following equation:

$$\frac{1}{OSC} \times 2^{14} \times PRESCALER \times 1000 \times 12 \text{ mS}$$

Before Watchdog time-out occurs, the program must clear the 14-bit timer by writing 1 to WDTC.6 (CLRW). After 1 is written to this bit, the 14-bit timer, prescaler and this bit will be reset on the next instruction cycle. The Watchdog timer is cleared on reset.



Watchdog Timer Block Diagram

Typical Watch-Dog time-out period when OSC = 20 MHz

PS2	PS1	PS0	WATCHDOG TIME-OUT PERIOD
0	0	0	19.66 mS
0	1	0	39.32 mS
0	0	1	78.64 mS
0	1	1	157.28 mS
1	0	0	314.57mS
1	0	1	629.14 mS
1	1	0	1.25 S
1	1	1	2.50 S

Clock

The W78L051C is designed to be used with either a crystal oscillator or an external clock. Internally, the clock is divided by two before it is used. This makes the W78L051C relatively insensitive to duty cycle variations in the clock. The W78L051C incorporates a built-in crystal oscillator. To make the oscillator work, a crystal must be connected across pins XTAL1 and XTAL2. In addition, a load capacitor must be connected from each pin to ground. An external clock source should be connected to pin XTAL1. Pin XTAL2 should be left unconnected. The XTAL1 input is a CMOS-type input, as required by the crystal oscillator.

Power Management

Idle Mode

The idle mode is entered by setting the IDL bit in the PCON register. In the idle mode, the internal clock to the processor is stopped. The peripherals and the interrupt logic continue to be clocked. The processor will exit idle mode when either an interrupt or a reset occurs.

Power-down Mode

When the PD bit of the PCON register is set, the processor enters the power-down mode. In this mode all of the clocks are stopped, including the oscillator. The only way to exit power-down mode is by a reset.

Reset

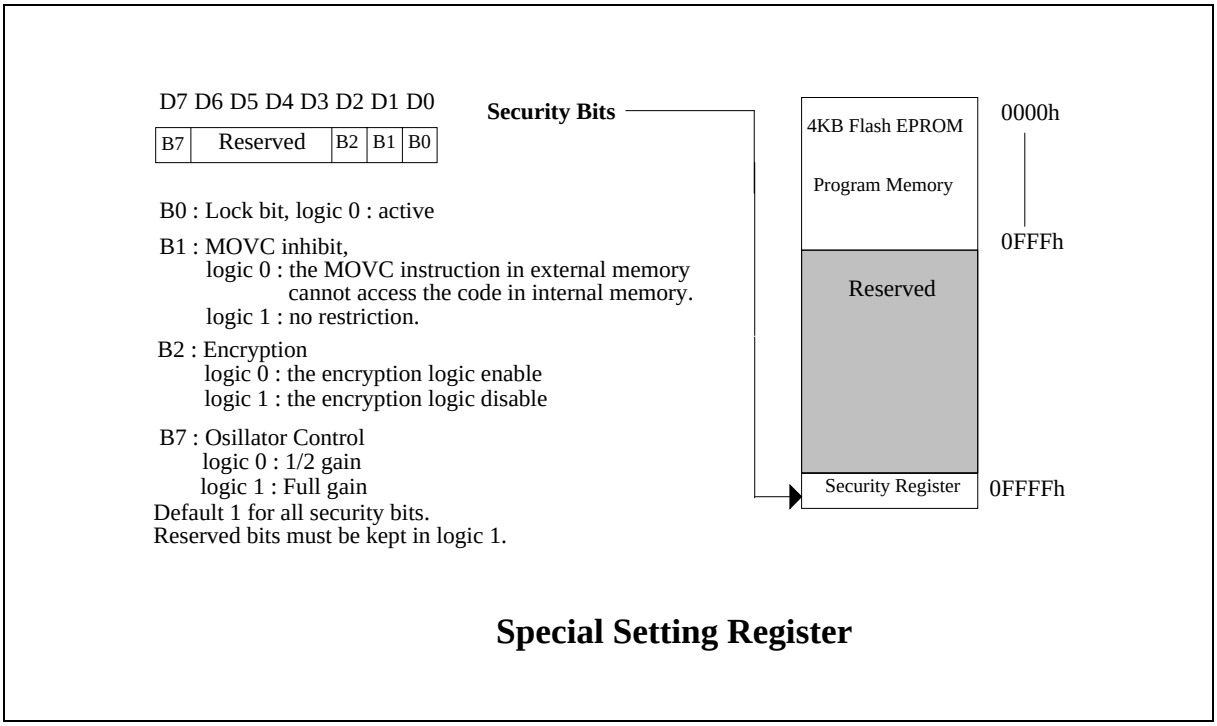
The external RESET signal is sampled at S5P2. To take effect, it must be held high for at least two machine cycles while the oscillator is running. An internal trigger circuit in the reset line is used to deglitch the reset line when the W78L051C is used with an external RC network. The reset logic also has a special glitch removal circuit that ignores glitches on the reset line.

During reset, the ports are initialized to FFH, the stack pointer to 07H, PCON (with the exception of bit 4) to 00H, and all of the other SFR registers except SBUF to 00H. SBUF is not reset.

6. ON-CHIP FLASH EPROM CHARACTERISTICS

7. SECURITY BITS

During the on-chip Flash EPROM operation mode, the Flash EPROM can be programmed and verified repeatedly. Until the code inside the Flash EPROM is confirmed OK, the code can be protected. The protection of Flash EPROM and those operations on it are described below. The W78L051C has a Special Setting Register, the Security Register, which can not be accessed in normal mode. The Security register can only be accessed from the Flash EPROM operation mode. Those bits of the Security Registers can not be changed once they have been programmed from high to low. They can only be reset through erase-all operation. The Security Register is addressed in the Flash EPROM operation mode by address #0FFFFh.



Special Setting Register

Lock bit

This bit is used to protect the customer's program code in the W78L051C. It may be set after the programmer finishes the programming and verifies sequence. Once this bit is set to logic 0, both the Flash EPROM data and Special Setting Registers can not be accessed again.

MOVC Inhibit

This bit is used to restrict the accessible region of the MOVC instruction. It can prevent the MOVC instruction in external program memory from reading the internal program code. When this bit is set to logic 0, a MOVC instruction in external program memory space will be able to access code only in the external memory, not in the internal memory. A MOVC instruction in internal program memory space will always be able to access the ROM data in both internal and external memory. If this bit is logic 1, there are no restrictions on the MOVC instruction.

Encryption

This bit is used to enable/disable the encryption logic for code protection. Once encryption feature is enabled, the data presented on port 0 will be encoded via encryption logic. Only whole chip erase will reset this bit.

8. ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	MIN.	MAX.	UNIT
DC Power Supply	V_{DD}–V_{SS}	-0.3	+7.0	V
Input Voltage	V_{IN}	V_{SS} -0.3	V_{DD} +0.3	V
Operating Temperature	T_A	0	70	°C
Storage Temperature	T_{ST}	-55	+150	°C

Note: Exposure to conditions beyond those listed under Absolute Maximum Ratings may adversely affect the life and reliability of the device.

9. DC CHARACTERISTICS

V_{SS} = 0V, T_A = 25° C, unless otherwise specified.

PARAMETER	SYM.	SPECIFICATION		UNIT	TEST CONDITIONS
		MIN.	MAX.		
Operating Voltage	V_{DD}	2.4	5.5	V	
Operating Current	I_{DD}	-	20	mA	No load V_{DD} = 5.5V
		-	3	mA	No load V_{DD} = 2.4V
Idle Current	I_{IDLE}	-	6	mA	V_{DD} = 5.5V, F_{OSC} = 20 MHz
		-	1.5	mA	V_{DD} = 2.4V, F_{OSC} = 12 MHz
Power Down Current	I_{PWDN}	-	50	µA	V_{DD} = 5.5V, F_{OSC} = 20 MHz
		-	20	µA	V_{DD} = 2.4V, F_{OSC} = 12 MHz
Input Current P1, P2, P3, P4	I_{IN1}	-50	+10	µA	V_{DD} = 5.5V V_{IN} = 0V or V_{DD}
Input Current RST	I_{IN2}	-10	+300	µA	V_{DD} = 5.5V 0 < V_{IN} < V_{DD}
Input Leakage Current P0, $\overline{EA}$	I_{LK}	-10	+10	µA	V_{DD} = 5.5V 0V < V_{IN} < V_{DD}
Logic 1 to 0 Transition Current P1, P2, P3, P4	I_{TL} [*4]	-500	-	µA	V_{DD} = 5.5V V_{IN} = 2.0V
Input Low Voltage	V_{IL1}	0	0.8	V	V_{DD} = 4.5V
P0, P1, P2, P3, P4, $\overline{EA}$		0	0.5	V	V_{DD} = 2.4V
Input Low Voltage	V_{IL2}	0	0.8	V	V_{DD} = 4.5V
RST[*1]		0	0.3	V	V_{DD} = 2.4V
Input Low Voltage	V_{IL3}	0	0.8	V	V_{DD} = 4.5V
XTAL1 [*3]		0	0.6	V	V_{DD} = 2.4V
Input High Voltage	V_{IH1}	2.4	V_{DD} +0.2	V	V_{DD} = 5.5V
P0, P1, P2, P3, P4, $\overline{EA}$		1.4	V_{DD} +0.2	V	V_{DD} = 2.4V
Input High Voltage	V_{IH2}	3.5	V_{DD} +0.2	V	V_{DD} = 5.5V
RST[*1]		1.7	V_{DD} +0.2	V	V_{DD} = 2.4V
Input High Voltage	V_{IH3}	3.5	V_{DD} +0.2	V	V_{DD} = 5.5V
XTAL1 [*3]		1.6	V_{DD} +0.2	V	V_{DD} = 2.4V

DC Characteristics, continued

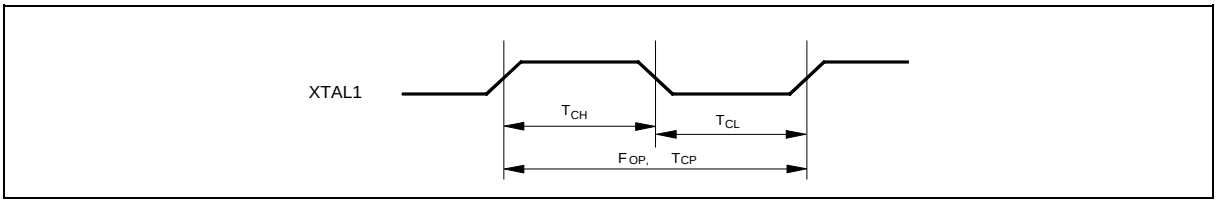
PARAMETER	SYM.	SPECIFICATION		UNIT	TEST CONDITIONS
		MIN.	MAX.		
Output Low Voltage	V_{OL1}	-	0.45	V	V_{DD} = 4.5V, I_{OL} = +2 mA
P1, P2, P3, P4		-	0.25	V	V_{DD} = 2.4V, I_{OL} = +1 mA
Output Low Voltage	V_{OL2}	-	0.45	V	V_{DD} = 4.5V, I_{OL} = +4 mA
P0, ALE, $\overline{PSEN}$ [*2]		-	0.25	V	V_{DD} = 2.4V, I_{OL} = +2 mA
Sink Current	I_{SK1}	4	12	mA	V_{DD} = 4.5V, Vin = 0.45V
P1, P2, P3, P4		1.8	5.4	mA	V_{DD} = 2.4V, Vin = 0.45V
Sink Current	I_{SK2}	8	16	mA	V_{DD} = 4.5V, Vin = 0.45V
P0, ALE, $\overline{PSEN}$		4.5	9	mA	V_{DD} = 2.4V, Vin = 0.45V
Output High Voltage	V_{OH1}	2.4	-	V	V_{DD} = 4.5V, I_{OH} = -100 μA
P1, P2, P3, P4		1.4	-	V	V_{DD} = 2.4V, I_{OH} = -8 μA
Output High Voltage	V_{OH2}	2.4	-	V	V_{DD} = 4.5V, I_{OH} = -400 μA
P0, ALE, $\overline{PSEN}$ [*2]		1.4	-	V	V_{DD} = 2.4V, I_{OH} = -200 μA
Source Current	I_{SR1}	-100	-250	μA	V_{DD} = 4.5V, Vin = 2.4V
P1, P2, P3, P4		-20	-50	μA	V_{DD} = 2.4V, Vin = 1.4V
Source Current	I_{SR2}	-8	-14	mA	V_{DD} = 4.5V, Vin = 2.4V
P0, ALE, $\overline{PSEN}$		-1.9	-3.8	mA	V_{DD} = 2.4V, Vin = 1.4V

Notes:
*1. RST pin is a Schmitt trigger input.
*2. P0, ALE and /PSEN are tested in the external access mode.
*3. XTAL1 is a CMOS input.
*4. Pins of P1, P2, P3, P4 can source a transition current when they are being externally driven from 1 to 0.

10. AC CHARACTERISTICS

The AC specifications are a function of the particular process used to manufacture the part, the ratings of the I/O buffers, the capacitive load, and the internal routing capacitance. Most of the specifications can be expressed in terms of multiple input clock periods (T_{CP}), and actual parts will usually experience less than a ±20 nS variation. The numbers below represent the performance expected from a 0.6micron CMOS process when using 2 and 4 mA output buffers.

Clock Input Waveform



PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTES
Operating Speed	F_{OP}	0	-	20	MHz	1
Clock Period	T_{CP}	50	-	-	nS	2
Clock High	T_{CH}	25	-	-	nS	3
Clock Low	T_{CL}	25	-	-	nS	3

Notes:
1. The clock may be stopped indefinitely in either state.
2. The T_{CP} specification is used as a reference in other specifications.
3. There are no duty cycle requirements on the XTAL1 input.

Program Fetch Cycle

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTES
Address Valid to ALE Low	T_{AAS}	1 T_{CP} -Δ	-	-	nS	4
Address Hold from ALE Low	T_{AAH}	1 T_{CP} -Δ	-	-	nS	1, 4
ALE Low to $\overline{PSEN}$ Low	T_{APL}	1 T_{CP} -Δ	-	-	nS	4
$\overline{PSEN}$ Low to Data Valid	T_{PDA}	-	-	2 T_{CP}	nS	2
Data Hold after $\overline{PSEN}$ High	T_{PDH}	0	-	1 T_{CP}	nS	3
Data Float after $\overline{PSEN}$ High	T_{PDZ}	0	-	1 T_{CP}	nS	
ALE Pulse Width	T_{ALW}	2 T_{CP} -Δ	2 T_{CP}	-	nS	4
$\overline{PSEN}$ Pulse Width	T_{PSW}	3 T_{CP} -Δ	3 T_{CP}	-	nS	4

Notes:
1. P0.0–P0.7, P2.0–P2.7 remain stable throughout entire memory cycle.
2. Memory access time is 3 T_{CP}.
3. Data have been latched internally prior to $\overline{PSEN}$ going high.
4. "Δ" (due to buffer driving delay and wire loading) is 20 nS.

Data Read Cycle

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTES
ALE Low to $\overline{RD}$ Low	TDAR	3 TCP -Δ	-	3 TCP +Δ	nS	1, 2
$\overline{RD}$ Low to Data Valid	TDDA	-	-	4 TCP	nS	1
Data Hold from $\overline{RD}$ High	TDDH	0	-	2 TCP	nS	
Data Float from $\overline{RD}$ High	TDDZ	0	-	2 TCP	nS	
$\overline{RD}$ Pulse Width	TDRD	6 TCP -Δ	6 TCP	-	nS	2

Notes:

1. Data memory access time is 8 TCP.
2. "Δ" (due to buffer driving delay and wire loading) is 20 nS.

Data Write Cycle

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
ALE Low to $\overline{WR}$ Low	TDAW	3 TCP -Δ	-	3 TCP +Δ	nS
Data Valid to $\overline{WR}$ Low	TDAD	1 TCP -Δ	-	-	nS
Data Hold from $\overline{WR}$ High	TDWD	1 TCP -Δ	-	-	nS
$\overline{WR}$ Pulse Width	TDWR	6 TCP -Δ	6 TCP	-	nS

Note: "Δ" (due to buffer driving delay and wire loading) is 20 nS.

Port Access Cycle

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Port Input Setup to ALE Low	TPDS	1 TCP	-	-	nS
Port Input Hold from ALE Low	TPDH	0	-	-	nS
Port Output to ALE	TPDA	1 TCP	-	-	nS

Note: Ports are read during S5P2, and output data becomes available at the end of S6P2. The timing data are referenced to ALE, since it provides a convenient reference.

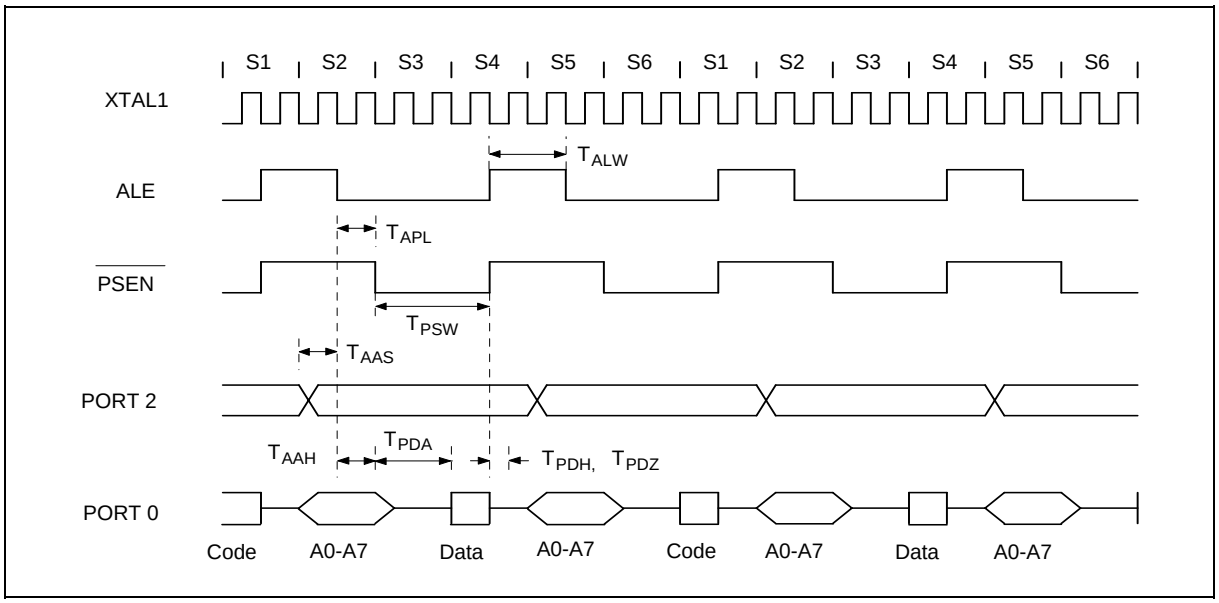
Program Operation

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
V_{PP} Setup Time	T_{VPS}	2.0	-	-	µS
Data Setup Time	T_{DS}	2.0	-	-	µS
Data Hold Time	T_{DH}	2.0	-	-	µS
Address Setup Time	T_{AS}	2.0	-	-	µS
Address Hold Time	T_{AH}	0	-	-	µS
$\overline{CE}$ Program Pulse Width for Program Operation	T_{PWP}	290	300	310	µS
OECTRL Setup Time	T_{OCS}	2.0	-	-	µS
OECTRL Hold Time	T_{OCH}	2.0	-	-	µS
$\overline{OE}$ Setup Time	T_{OES}	2.0	-	-	µS
$\overline{OE}$ High to Output Float	T_{DFP}	0	-	130	nS
Data Valid from $\overline{OE}$	T_{OEV}	-	-	150	nS

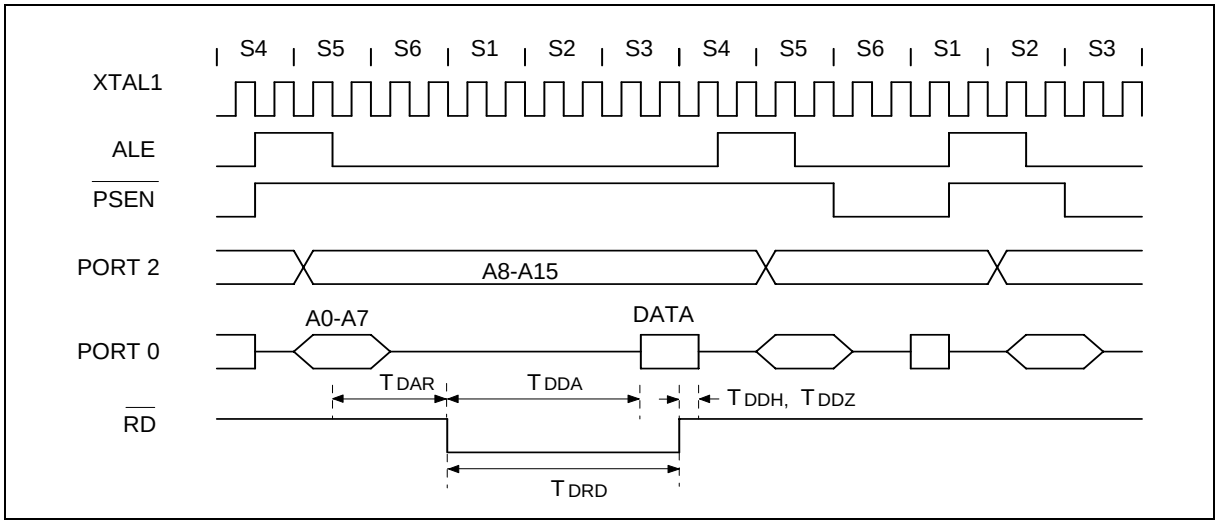
Note: Flash data can be accessed only in flash mode. The RST pin must pull in V_{IH} status, the ALE pin must pull in V_{IL} status, and the $\overline{PSEN}$ pin must pull in V_{IH} status.

11. TIMING WAVEFORMS

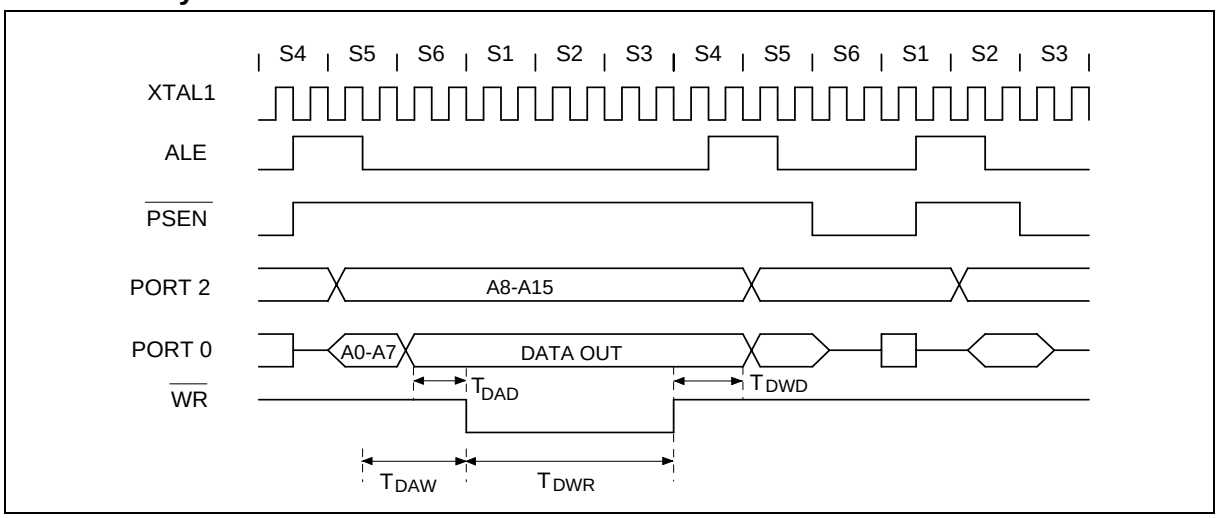
Program Fetch Cycle



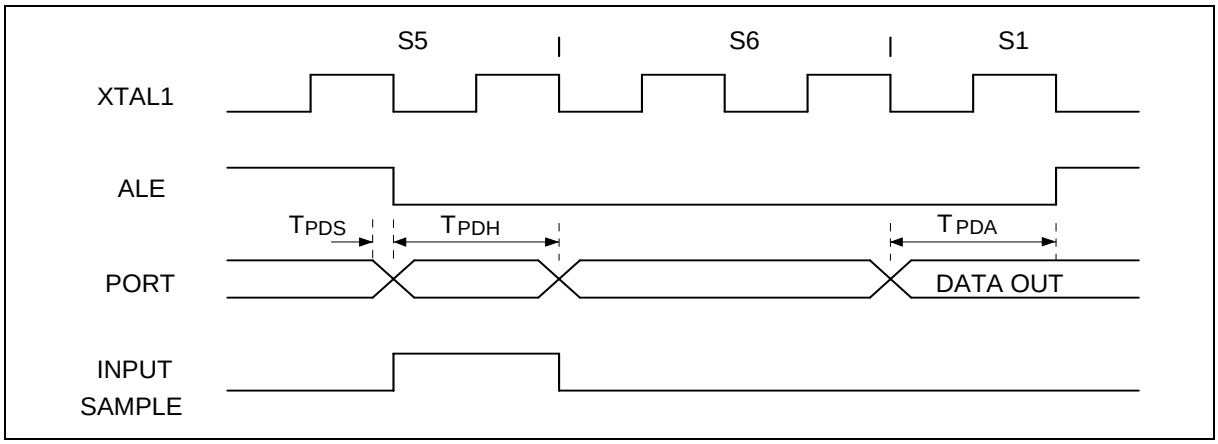
Data Read Cycle



Data Write Cycle



Port Access Cycle



12. TYPICAL APPLICATION CIRCUITS

Expanded External Program Memory and Crystal

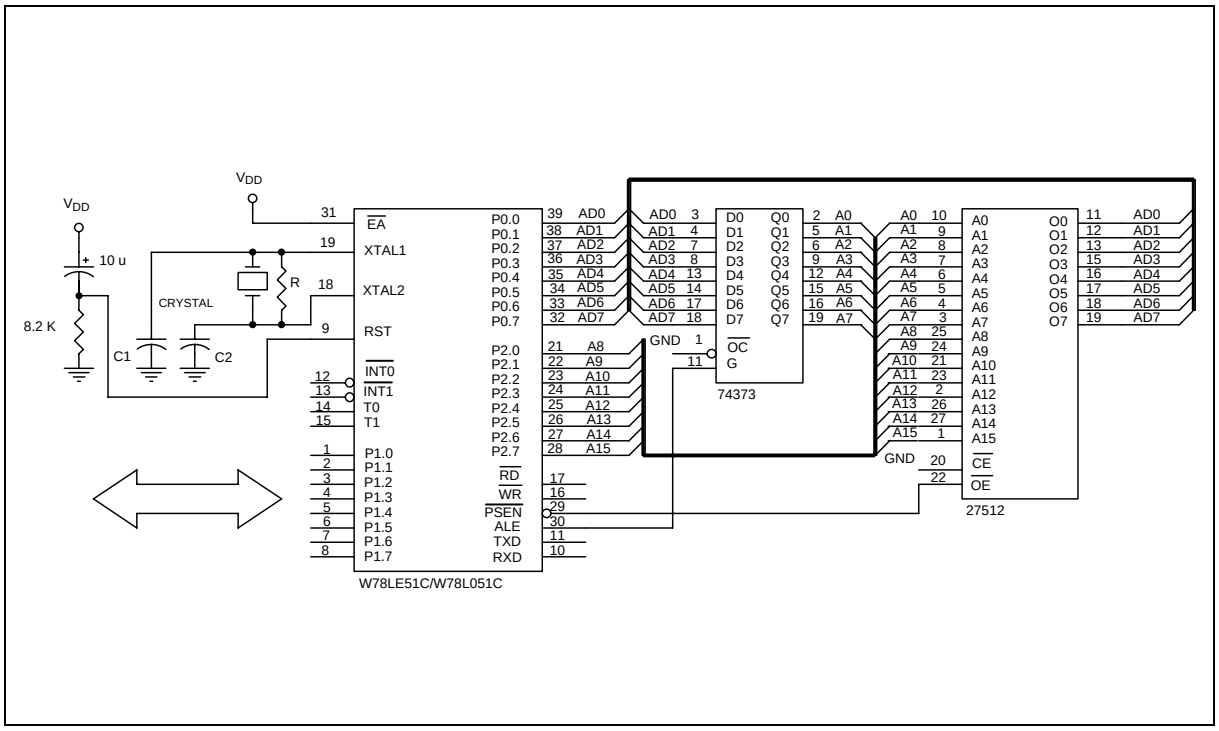


Figure A

CRYSTAL	C1	C2	R
16 MHz	30P	30P	-
20 MHz	15P	15P	-

Above table shows the reference values for crystal applications (full gain).

Note: C1, C2, R components refer to Figure A.

Expanded External Data Memory and Oscillator

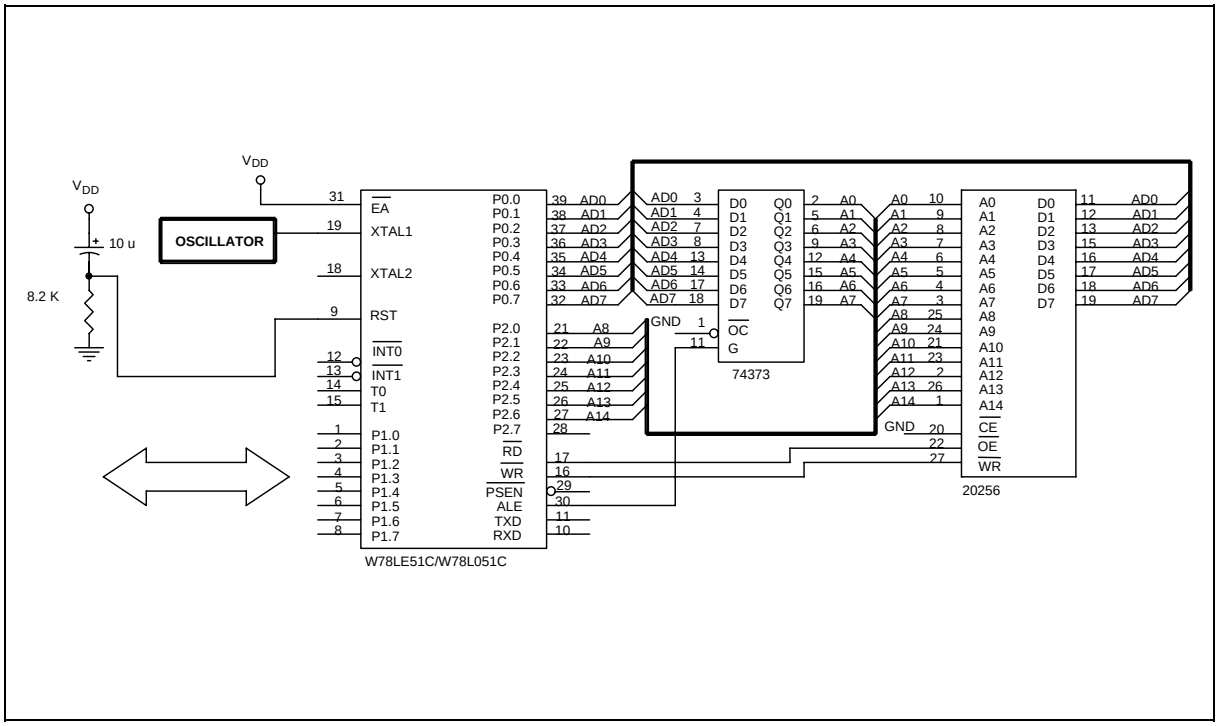
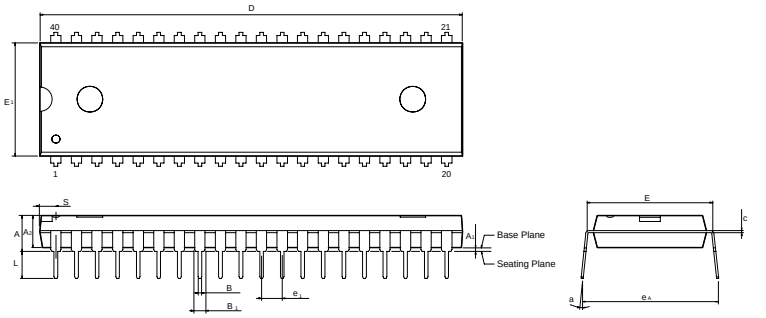


Figure B

13. PACKAGE DIMENSIONS

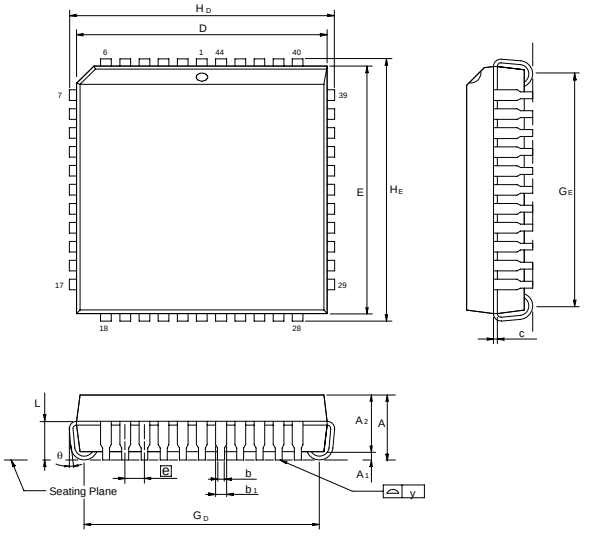
40-pin DIP



Symbol	Dimension in inch			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	—	—	0.210	—	—	5.334
A_1	0.010	—	—	0.254	—	—
A_2	0.150	0.155	0.160	3.81	3.937	4.064
B	0.016	0.018	0.022	0.406	0.457	0.559
B_1	0.048	0.050	0.054	1.219	1.27	1.372
c	0.008	0.010	0.014	0.203	0.254	0.356
D	—	2.055	2.070	—	52.20	52.58
E	0.590	0.600	0.610	14.986	15.24	15.494
E_1	0.540	0.545	0.550	13.72	13.84	13.97
e_1	0.090	0.100	0.110	2.286	2.54	2.794
L	0.120	0.130	0.140	3.048	3.302	3.556
a	0	—	15	0	—	15
e_A	0.630	0.650	0.670	16.00	16.51	17.01
S	—	—	0.090	—	—	2.286

Notes:
1. Dimension D Max. & S include mold flash or tie bar burrs.
2. Dimension E1 does not include interlead flash.
3. Dimension D & E1 include mold mismatch and are determined at the mold parting line.
4. Dimension B1 does not include dambar protrusion/intrusion.
5. Controlling dimension: Inches.
6. General appearance spec. should be based on final visual inspection spec.

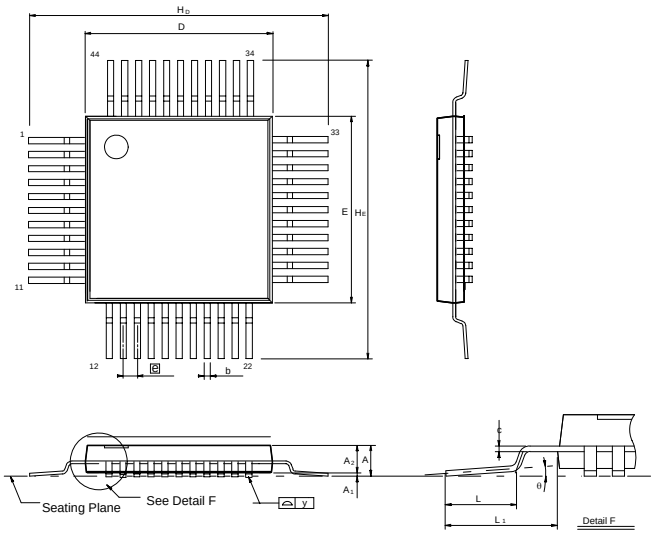
44-pin PLCC



Symbol	Dimension in inch			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	—	—	0.185	—	—	4.699
A_1	0.020	—	—	0.508	—	—
A_2	0.145	0.150	0.155	3.683	3.81	3.937
b_1	0.026	0.028	0.032	0.66	0.711	0.813
b	0.016	0.018	0.022	0.406	0.457	0.559
c	0.008	0.010	0.014	0.203	0.254	0.356
D	0.648	0.653	0.658	16.46	16.59	16.71
E	0.648	0.653	0.658	16.46	16.59	16.71
e	0.050 BSC			1.27 BSC		
G_D	0.590	0.610	0.630	14.99	15.49	16.00
G_E	0.590	0.610	0.630	14.99	15.49	16.00
H_D	0.680	0.690	0.700	17.27	17.53	17.78
H_E	0.680	0.690	0.700	17.27	17.53	17.78
L	0.090	0.100	0.110	2.296	2.54	2.794
y	—	—	0.004	—	—	0.10

Notes:
1. Dimension D & E do not include interlead flash.
2. Dimension b1 does not include dambar protrusion/intrusion.
3. Controlling dimension: Inches
4. General appearance spec. should be based on final visual inspection spec.

44-pin PQFP



Symbol	Dimension in inch			Dimension in mm		
	Min.	Nom.	Max.	Min.	Nom.	Max.
A	---	---	---	---	---	---
A_1	0.002	0.01	0.02	0.05	0.25	0.5
A_2	0.075	0.081	0.087	1.90	2.05	2.20
b	0.01	0.014	0.018	0.25	0.35	0.45
c	0.004	0.006	0.010	0.101	0.152	0.254
D	0.390	0.394	0.398	9.9	10.00	10.1
E	0.390	0.394	0.398	9.9	10.00	10.1
e	0.025	0.031	0.036	0.635	0.80	0.952
H_D	0.510	0.520	0.530	12.95	13.2	13.45
H_E	0.510	0.520	0.530	12.95	13.2	13.45
L	0.025	0.031	0.037	0.65	0.8	0.95
L_1	0.051	0.063	0.075	1.295	1.6	1.905
y	—	—	0.003	—	—	0.08
θ	0°	—	7°	0°	—	7°

Notes:

1. Dimension D & E do not include interlead flash.
2. Dimension b does not include dambar protrusion/intrusion.
3. Controlling dimension: Millimeter
4. General appearance spec. should be based on final visual inspection spec.

14. REVISION HISTORY

VERSION	DATE	PAGE	REASONS FOR CHANGE
A1	May 19, 2005		Initial Issued
A2	October 2, 2006		Remove block diagram Change operating frequency into 20MHz
A3	December 4, 2006	2	Remove all Leaded package parts

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